

IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-24 (Canceled)

25. (Original) A processing method for fuse structure, comprising the steps of:

- providing a structure;
- forming a first conductive layer and a second conductive layer on part of the structure;
- forming a first dielectric layer on the first conductive layer, the second conductive layer and the structure;
- forming a first opening on the first dielectric layer, exposing the first conductive layer and the second conductive layer;
- implanting a first conductive plug to penetrate the first conductive layer via the first opening;
- forming a third conductive layer and a fourth conductive layer on part of the first dielectric layer;
- forming a second dielectric layer on the third conductive layer, the fourth conductive layer and the first dielectric layer;
- forming a second opening on the second dielectric layer, exposing the first opening, the third conductive layer and the fourth conductive layer;
- implanting the second conductive plug to penetrate the second dielectric layer via the second opening;
- forming a fifth conductive layer, a sixth conductive layer, a seventh conductive layer, a eighth conductive layer, a ninth conductive layer and a tenth conductive layer on part of the second dielectric layer, wherein a third conductive plug is electrically connected to the fourth conductive layer and the fifth conductive layer, a fourth conductive plug is electrically connected to the second conductive layer and the sixth conductive layer, the third conductive layer is electrically connected to the ninth conductive layer and the eighth conductive layer is electrically connected to the first conductive layer.

26. (Currently Amended) A processing method for fuse structure, comprising the steps of:

forming a substrate;

forming a eleventh conductive layer, a twelfth conductive layer, a thirteenth conductive layer and a fourteenth conductive layer on part of the substrate;

forming a first dielectric layer on the eleventh conductive layer, the twelfth conductive layer, the thirteenth conductive layer, the fourteenth conductive layer and the substrate;

forming a fifteenth conductive layer, a sixteenth conductive layer, a seventeenth conductive layer, a ~~eighteen~~ eighteenth conductive layer on part of the first dielectric layer;

forming a second dielectric layer on the fifteenth conductive layer, the sixteenth conductive layer, the seventeenth conductive layer, the ~~eighteen~~ eighteenth conductive layer and the first dielectric layer;

forming an opening on the first dielectric layer and second dielectric layer, exposing the eleventh conductive layer, the twelfth conductive layer, the thirteenth conductive layer, fourteenth conductive layer, fifteenth conductive layer, sixteenth conductive layer, the seventeenth conductive layer and the ~~eighteen~~ eighteenth conductive layer;

implanting a conductive plug in the opening, to penetrate the first dielectric layer and the second dielectric layer; and

forming a nineteenth conductive layer, a twentieth conductive layer, a twenty first conductive layer, twenty second conductive layer, a twenty third conductive layer, a twenty fourth conductive layer, a twenty fifth conductive layer, a twenty sixth conductive layer, a twenty seventh conductive layer and a twenty eighth conductive layer on part of the second dielectric layer, wherein a eleventh conductive plug is electrically connected to the fifteenth conductive layer and nineteenth conductive layer, a twelfth conductive plug is electrically connected to the eleventh conductive layer and the twentieth conductive layer, a thirteenth conductive plug is electrically connected to the twenty sixth conductive layer and the twelfth conductive layer, a fourteenth conductive plug is electrically connected to the twenty seventh conductive layer and the sixteenth conductive layer, a fifteenth conductive plug is electrically connected to the twenty first conductive layer and the thirteenth conductive layer, a sixteenth conductive ~~layer~~ plug is electrically connected to the twenty second conductive layer and the seventeenth conductive layer, a seventeenth conductive plug is electrically connected to the twenty fourth conductive layer and eighteenth conductive layer, and a eighteenth conductive plug is electrically connected to the twenty fifth conductive layer and the fourteenth conductive layer.